

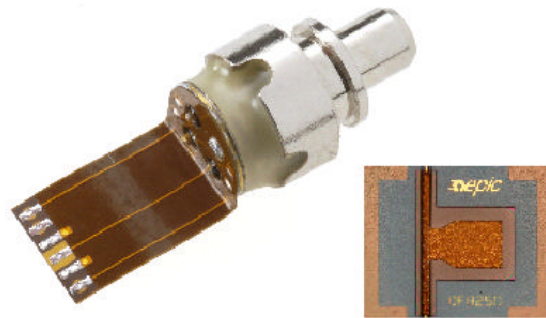
For immediate release

OEpic Offers Complete 1310 nm 10 Gb/s Optical Front-End Solution For Low Cost Next Generation Transceivers

OEpic's 10G TO-Flex™ chipset addresses need for complete low-cost, multi-standard 1310 nm optical front-end solution for new small form-factor transceivers, such as XENPAK, X2, XPAK and XFP.

SUNNYVALE, CA, MARCH 19, 2003

– OEpic, Inc. introduced today a 10 Gb/s 1310 nm optoelectronic front-end transmitter incorporating flex board interconnection technology (**TO-Flex™**) for low cost, next generation 10 Gb/s optical transceivers, such as XENPAK, X2, XPAK and XFP. The transmitter complements the company's 1310 nm optical receiver chipset released earlier, providing a complete optical front-end (OFE) chipset solution for intermediate and long-reach (IEEE 10GBASE-L) fiber optic applications. The Sunnyvale, California-based semiconductor company designs, manufactures and sells Optoelectronic Integrated Solutions for next generation high-speed optical communications systems.



OEpic's 1310 nm 10G DFB laser TOSA/ROSA in TO-Flex Provides Low Cost, Multi-Standard Solution for Next -Generation Transceivers

“We are aggressively expanding our product line based on the low cost, industry standard TO-Flex optical package platform.” said Dr. Yi-Ching Pao, Founder, President and CEO of OEpic. “Our new 1310 nm products coupled with our well-accepted 10G 850 nm VSR optical front-end chipset make OEpic the most complete optical front-end supplier in the industry offering products with high performance at the lowest price.

The 10 Gb/s front-end chipset is designed for 10 G Ethernet and Fibre Channel datacom applications in Storage Area Networks (SAN), Local Area Networks (LAN) and Metro Networks, such as 1310 nm datacom products meeting the IEEE 802.3ae LR standard. TO-Flex permits the use of the OEpic OFE chipset in all current 10 Gb/s transceiver multiple source agreements (MSAs).

The 10 Gb/s 1310 nm optical front-end transmitter consists of a distributed feedback (DFB) laser with internal monitoring photodetector for reaches up to 10 km (or an optional Fabry-Perot laser for 600 m to 2 km reaches). Optical transceiver OEMs can use OEpic's other products, such as laser driver amplifier for a complete transmitter chipset.

Product data sheets are available at <http://www.oepic.com/hm021206/Products.asp?id=2>
The TO-Flex platform photo is available at
<http://www.oepic.com/co/news/photos/photo4.jpg>

OEpic's 10G TO-Flex 1310nm OFE products will be featured at the Optical Fiber Communications Conference & Exhibition (OFC 2003) in Atlanta, GA, March 23-28, 2003 in Booth 7065. For information on OFC 2003, please visit <http://www.ofcconference.com/>.

Technical details of the 10G TO-Flex 1310 nm optical front-end chipset:

- 1) The LD1030 Transmitter consists of a 1310 nm DFB laser with internal monitor photodiode. The device provides a typical optical output power of 0.9 mW at 35 mA and operates up to 12.5 Gb/s. It is available in an internally-matched 10 Gb/s TO-Flex package with LC or SC connector.
- 2) The LF1030 Transmitter consists of a 1310 nm FP laser with internal monitor photodiode. The device provides a similar speed performance to the DFB version at a lower cost. It is available in an internally-matched 10 Gb/s TO-Flex package with LC or SC connector.
- 3) The PT1030 Receiver consists of a PIN photodetector, integrated with an InGaP-HBT transimpedance amplifier (TIA). The device has a low power consumption of only 120 mW and a minimum sensitivity of -15 dBm at 1310 nm. It is available in an internally matched 10 Gb/s TO-Flex package with LC or SC connector.
- 4) The DL1003 Laser Driver can be used with either the DFB or FP laser products. The device is biased at 5V and 115 mA for a total power consumption of 575 mW. It is available in a 3 mm QFN package.

Availability:

The 10G TO-Flex 1310 nm OFE chipset and evaluation boards will be available for sampling and evaluation in May 2003. Volume quantities will be available in Q3 of 2003.

About OEpic:

OEpic (pronounced 'epic') designs, manufactures and sells complete optical front-end chipset solutions which integrate optical components with high-speed electronics. These are used by OEMs to create fast, highly integrated fiber optic subsystems that allow the development of innovative, next-generation optical communications systems.

OEpic was founded in July 2000 in Sunnyvale, California, by an experienced team with backgrounds in optoelectronic and microwave technologies at leading firms.

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